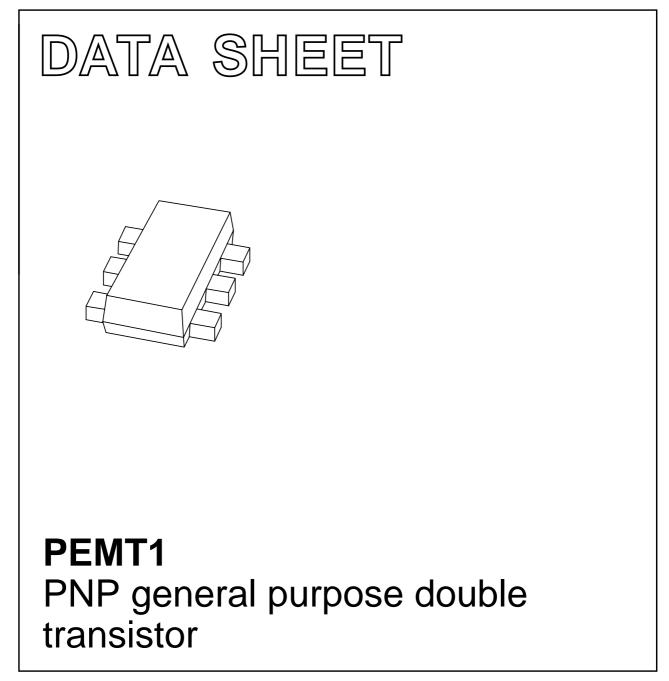
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Sep 25 2001 Nov 07



#### FEATURES

- 300 mW total power dissipation
- Very small 1.6 × 1.2 mm ultra thin package
- Self alignment during soldering due to straight leads
  Replaces two SC-75/SC-89 packaged transistors on same PCB area
- Reduced required PCB area
- Reduced pick and place costs.

#### APPLICATIONS

• General purpose switching and amplification.

#### DESCRIPTION

PNP transistor pair in a SOT666 plastic package. NPN complement: PEMX1.

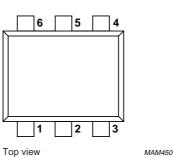
#### MARKING

TYPE NUMBER	MARKING CODE
PEMT1	FF

#### •

#### PINNING

PIN		DESCRIPTION
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
6, 3	collector	TR1; TR2



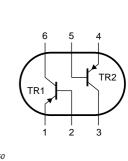


Fig.1 Simplified outline (SOT666) and symbol.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transi	stor				
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	V
I <sub>C</sub>	collector current (DC)		-	-100	mA
I <sub>CM</sub>	peak collector current		_	-200	mA
I <sub>BM</sub>	peak base current		-	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C
Per device	•		•		•
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	300	mW

2

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

### PEMT1

### PEMT1

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

#### Notes

- 1. Transistor mounted on an FR4 printed-circuit board.
- 2. The only recommended soldering is reflow soldering.

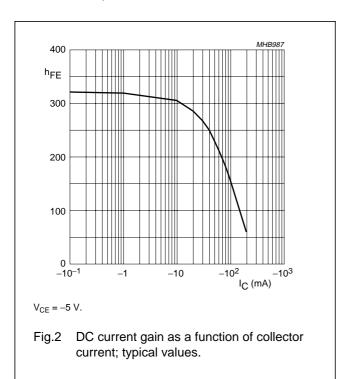
#### CHARACTERISTICS

 $T_{amb}$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transis	stor	·		·	1
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -30 \text{ V}; \text{ I}_{E} = 0$	-	-100	nA
		$V_{CB} = -30 \text{ V}; \text{ I}_{E} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-10	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -4 V; I_C = 0$	-	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -6 \text{ V}; \text{ I}_{C} = -1 \text{ mA}$	120	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_{\rm C} = -50$ mA; $I_{\rm B} = -5$ mA; note 1	_	-200	mV
C <sub>c</sub>	collector capacitance	$V_{CB} = -12 \text{ V}; \text{ I}_{E} = \text{ I}_{e} = 0; \text{ f} = 1 \text{ MHz}$	-	2.2	pF
f <sub>T</sub>	transition frequency	$V_{CE} = -12 \text{ V}; I_C = -2 \text{ mA};$ f = 100 MHz	100	-	MHz

#### Note

1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 



X

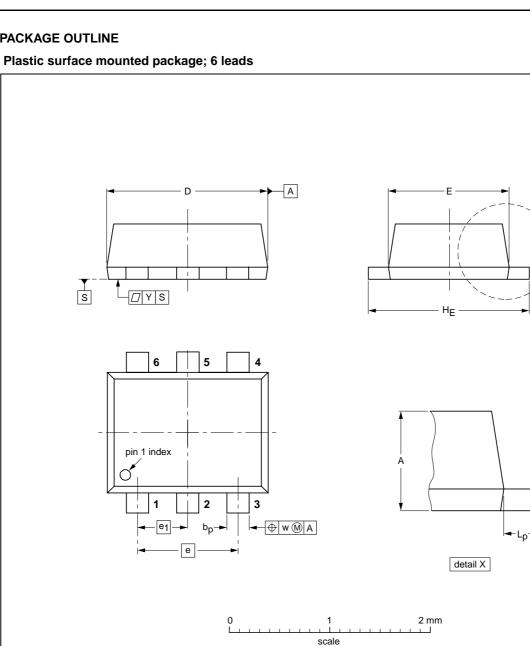
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PEMT1

## PNP general purpose double transistor

#### PACKAGE OUTLINE



# DIMENSIONS (mm are the original dimensions)

UNIT	A	b <sub>p</sub>	С	D	Е	е	e <sub>1</sub>	H <sub>E</sub>	Lp	w	У
mm	0.6 0.5	0.27 0.17	0.18 0.08	1.7 1.5	1.3 1.1	1.0	0.5	1.7 1.5	0.3 0.1	0.1	0.1

OUTLINE		REFERENCES				ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE	
SOT666					$\square \bigcirc$	<del>01-01-04</del> 01-08-27	

# **SOT666**

PEMT1

#### DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

#### Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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PEMT1

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PEMT1

NOTES

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